

17.08.2023

0	17.08.2023	New release.	WYC	LSB

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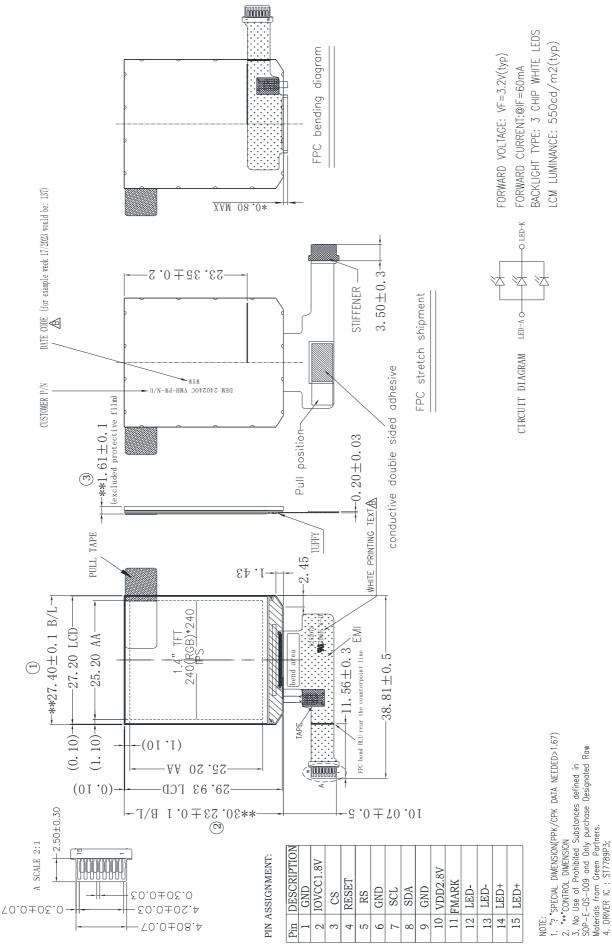
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1.0 GENERAL SPECIFICATION

Item	Contents	Unit
Display Mode	1,4" TFT Transmissive/IPS/Normally Black	-
Module Outer Dimension	27.40 x 30.23 x 1.61 (Excluded FPC length)	mm
Pixel Size	0.105 × 0.105	mm
Active Area	25.20 x 25.20	mm
Number of Dots	240 x RGB x 240	dots
Viewing Direction	All Direction	O'clock
Pixel Arrangement	RGB Vertical Stripe	-
Backlight	LED White Backlight	-
Driver IC	ST7789P3 (Sitronix)	-
Interface Type	4-line SPI	-
Number Of Colors	262k	-
Operating Temperature	-20 ~ +60	°C
Storage Temperature	-30 ~ +70	°C

Remarks: Normal Operating Condition is Temperature 15°C~35°C, Humidity 45%RH ~ 75%RH, Atmospheric Pressure 86kPa ~ 106kPa.

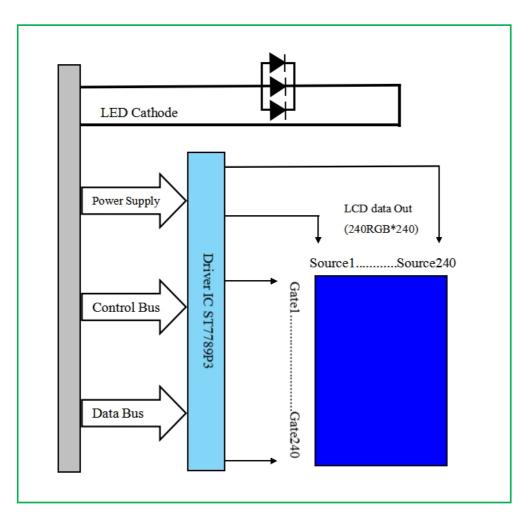
2.0 OUTLINE DRAWING



3.0 INTERFACE PIN DESCRIPTION

Pin No.	Symbol	Pin Description
1	GND	Ground
2	IOVCC1.8V	Power Supply for I/O System.
3	CS	Chip selection pin,Low-active
4	RESET	Reset Signal Input Pin
5	RS	Display data/command selection pin
6	GND	Ground
7	SCL	Serial clock signal interface
8	SDA	Serial Data Transport Interface
9	GND	Ground
10	VDD2.8V	Power Supply for Analog, Digital System and Booster Circuit.
11	FMARK	1
12	LED-	LED backlight cathode.
13	LED-	LED backlight cathode.
14	LED+	LED backlight anode.
15	LED+	LED backlight anode.

4.0 BLOCK DIAGRAM



5.0 OPERATING PRINCIPLE & DRIVING METHOD

5.1 Please refer to ST7789P3(V1.0) IC data sheet.

5.2 Instruction Description (based on IC spec ver as stated in 6.1 where the product is designed). This instruction description is for reference only. Customer is encouraged to always refer to the latest IC specification when developing application system platform.

5.3 Recommended initial codes.

void LCD_Init(void)

HW Reset();

Delay(120);//delay 120ms

WriteComm(0x11);

Delay(120);

WriteComm(0xB2); WriteData(0x0C); WriteData(0x0C); WriteData(0x00); WriteData(0x33); WriteData(0x33);

WriteComm(0x35); WriteData(0x00);

WriteComm(0x36); WriteData(0xC0);

WriteComm(0x3A); WriteData(0x05);

WriteComm(0xB7); WriteData(0x02);

WriteComm(0xBB); WriteData(0x31); //Vcom=1.35V

WriteComm(0xC0); WriteData(0x2C);

WriteComm(0xC2); WriteData(0x01);

WriteComm(0xC3); WriteData(0x19); //GVDD=4.8V

WriteComm(0xC4); WriteData(0x20); //VDV

WriteComm(0xC6); WriteData(0x0F); //60Hz

WriteComm(0xD0); WriteData(0xA4); WriteData(0xA1); WriteComm(0xD6); WriteData(0xA1);

WriteComm(0xE0); WriteData(0xF0); WriteData(0x04); WriteData(0x0A); WriteData(0x09); WriteData(0x0A); WriteData(0x27); WriteData(0x2C); WriteData(0x43); WriteData(0x42); WriteData(0x38); WriteData(0x13); WriteData(0x13); WriteData(0x27); WriteData(0x2B); WriteComm(0xE1); WriteData(0xF0); WriteData(0x05); WriteData(0x08); WriteData(0x0A); WriteData(0x08); WriteData(0x04); WriteData(0x2C); WriteData(0x43); WriteData(0x41); WriteData(0x3A); WriteData(0x16); WriteData(0x16); WriteData(0x28); WriteData(0x2C); WriteComm(0x29);

WriteComm(0x21);

WriteComm(0x2C);
}

Notes:

- 1) These initial codes are only for reference, Customer should optimize above setting according to the display pattern and application used.
- 2) Customer is advised to refer to "General Handling Precaution of LCD Modules" section in this product specification regarding the operating precaution of LCD modules, when optimizing the display initialization setting.
- 3) DISPLAY Elektronik GmbH will use above initial code for production testing by default. Customer is advised to highlight to DISPLAY Elektronik GmbH in case that initial code setting in customer application is different with above initial code. Reason is to ensure DISPLAY Elektronik GmbH testing is in-line with customer application as close as possible for good quality control.

5.4 Power On/Off Sequence

VDDI and VDD can be applied in any order.

In CABC function application, VDDI power on need delay 5ms after VDD has been supplied.

VDD and VDDI can be power down in any order.

During power off, if LCD is in the Sleep Out mode, VDD and VDDI must be powered down minimum 120msec after RESX has been released.

During power off, if LCD is in the Sleep In mode, VDDI or VDD can be powered down minimum 0msec after RESX has been released.

CSX can be applied at any timing or can be permanently grounded. RESX has priority over CSX.

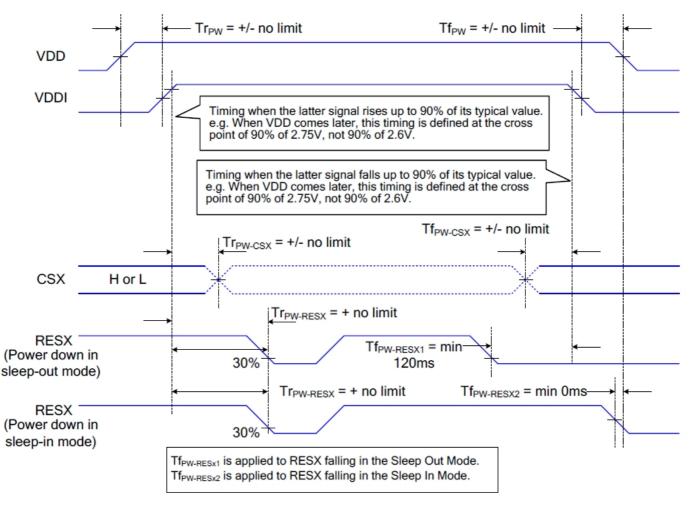
Note 1: There will be no damage to the display module if the power sequences are not met.

Note 2: There will be no abnormal visible effects on the display panel during the Power On/Off Sequences.

Note 3: There will be no abnormal visible effects on the display between end of Power On Sequence and before receiving Sleep Out command. Also between receiving Sleep In command and Power Off Sequence.

Note 4: If RESX line is not held stable by host during Power On Sequence as defined in the sequence below, then it will be necessary to apply a Hardware Reset (RESX) after Host Power On Sequence is complete to ensure correct operation. Otherwise function is not guaranteed.

The power on/off sequence is illustrated below

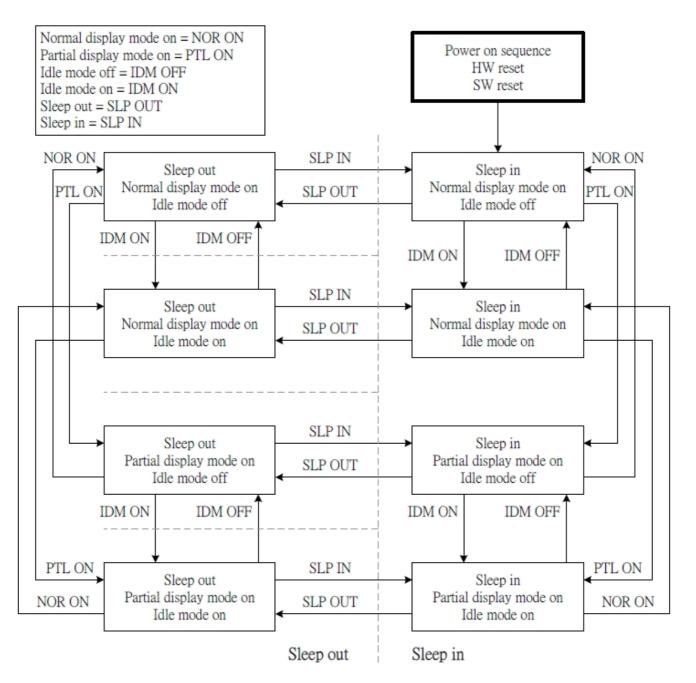


8.15.1 Uncontrolled Power Off

The uncontrolled power-off means a situation which removed a battery without the controlled power off sequence. It will neither damage the module or the host interface.

If uncontrolled power-off happened, the display will go blank and there will not any visible effect on the display (blank display) and remains blank until "Power On Sequence" powers it up.

5.5 Power Flow Chart



5.6 Timing Characteristics

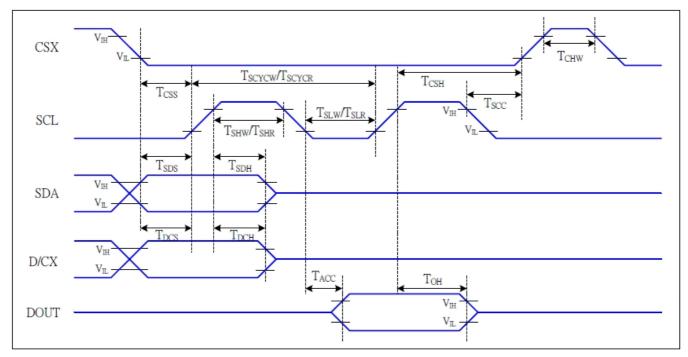


Figure 5 4-line serial Interface Timing Characteristics

	A				11	
Signal	Symbol	Parameter	MIN	MAX	Unit	Description
	T _{CSS}	Chip select setup time (write)	15	-	ns	
	Тсян	Chip select hold time (write)	15	-	ns	
CSX	Tcss	Chip select setup time (read)	60	-	ns	
	Tscc	Chip select hold time (read)	65	-	ns	
	Тснw	Chip select "H" pulse width	40	-	ns	
	Tscycw	Serial clock cycle (Write)	16	-	ns	unite commend & date
	T _{SHW}	SCL "H" pulse width (Write)	7	-	ns	-write command & data
	Tslw	SCL "L" pulse width (Write)	7	-	ns	ram
SCL	TSCYCR	Serial clock cycle (Read)	150	-	ns	
	T _{SHR}	SCL "H" pulse width (Read)	60	-	ns	-read command & data
	T _{SLR}	SCL "L" pulse width (Read)	60	-	ns	ram
	TDCS	D/CX setup time	10	-	ns	
D/CX T _{DCH}		D/CX hold time	10	-	ns	
SDA	T _{SDS}	Data setup time	7	-	ns	
(DIN)	T _{SDH}	Data hold time	7	-	ns	
DOUT	TACC	Access time	10	50	ns	For maximum CL=30pF
DOUT	Тон	Output disable time	15	50	ns	For minimum CL=8pF

VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=25℃

Table 6 4-line serial Interface Characteristics

Note1 : The rising time and falling time (Tr, Tf) of input signal are specified at 15 ns or less. Logic high and low levels are specified as

30% and 70% of VDDI for Input signals.

Note2 : In the read sequence of Serial interface, the 500nsec delay time is needed between read command and first read clock

5.7 Reset Timing

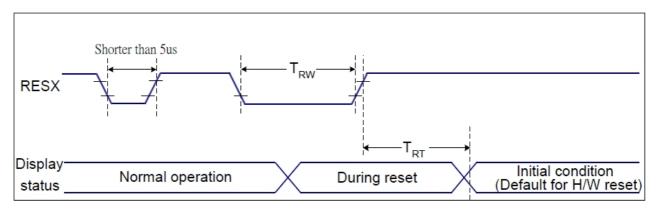


Figure 7 Reset Timing

VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=25℃

Related Pins	Symbol	Parameter	MIN	MAX	Unit
	TRW	Reset pulse duration	10	-	us
RESX	TRT	Peast served	-	5 (Note 1, 5)	ms
		Reset cancel	-	120 (Note 1, 6, 7)	ms

Table 8 Reset Timing

Notes:

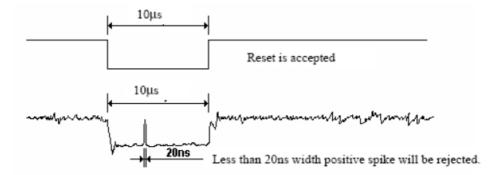
1. The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from NVM (or similar device) to registers. This loading is done every time when there is HW reset cancel time (tRT) within 5 ms after a rising edge of RESX.

2. Spike due to an electrostatic discharge on RESX line does not cause irregular system reset according to the table below:

RESX Pulse	Action		
Shorter than 5us	Reset Rejected		
Longer than 9us	Reset		
Between 5us and 9us	Reset starts		

3. During the Resetting period, the display will be blanked (The display is entering blanking sequence, which maximum time is 120 ms, when Reset Starts in Sleep Out –mode. The display remains the blank state in Sleep In –mode.) and then return to Default condition for Hardware Reset.

4. Spike Rejection also applies during a valid reset pulse as shown below:



- 5. When Reset applied during Sleep In Mode.
- 6. When Reset applied during Sleep Out Mode.
- 7. It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for

120msec.

6.0 **ABSOLUTE MAXIMUM RATINGS** (Ta = 25°C, Vss = 0 V, IOVCC1.8V=VDDI, VDD2 8V=VDD)

Parameter	Symbol	Min	Тур.	Max	Unit
System Voltage	V _{DD}	-0.3	-	4.6	V
Interface Operation Voltage	VDDI	-0.3	-	4.0	V
Driver Supply Voltage	VGH-VGL	-0.3	-	30	V
Input Voltage	V _{IN}	-0.3	-	4.0	V
Output Voltage	Vo	-0.3	-	4.0	V
Operating Temperature	Тор	-20	-	60	°C
Storage Temperature	Tst	-30	-	70	°C

7.0 ELECTRICAL CHARACTERISTICS (Ta = 25°C, Vss = 0 V, IOVCC1.8V=VDDI, VDD2.8V=VDD)

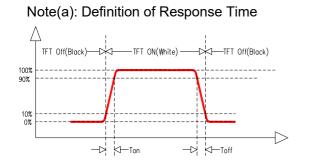
Parameter	Symbol	Condition	Min	Тур.	Max	Unit
System Voltage	V _{DD}	-	2.4	2.8	3.3	V
Interface Operation Voltage	VDDI	-	1.65	1.8	3.3	V
Gate On Power	VGH	-	-	12.2	-	V
Gate Off Power	VGL	-	-	-8.23	-	V
Vcom	Vcom	-	-	0	-	V
Logic High Input Voltage	VIH	-	0.7VDDI	-	VDDI	V
Logic Low Input Voltage	V _{IL}	-	VSS	-	0.3VDDI	V
Logic High Output Voltage	V _{OH}	IOH=-1.0mA	0.8VDDI	-	VDDI	V
Logic Low Output Voltage	V _{OL}	IOL= +1.0mA	VSS		0.2VDDI	V
LCM Supply Current	I _{LCM}	-	-	6.7	10	mA

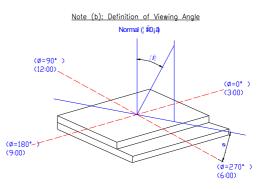
8.0 ELECTRO-OPTICAL CHARACTERISTICS

No	Item Symbol		Condi	tion	Min.	Тур.	Max.	Unit	Note	
1	Response Tir	ne	$T_{on} + T_{off}$	$\theta = \phi =$	= 0º	-	30	40	ms	(a)
2	Contrast Rat	io	CR	$\theta = \phi =$	= 0º	800	900	-	-	(c)
			3:00	φ = ()°	70	80	-	Deg	
3	Viewing Ang	le	9:00	φ = 18	30°	70	80	-	Deg	(b)
3	(CR ≥ 10)		12:00	φ = 9	0°	70	80	-	Deg	(b)
			6:00	φ = 27	φ = 270°		80	-	Deg	
4	Brightness on LCM		L _{LCM}	$\Phi = 0^{\circ}$	25°C	500	550		cd/m 2	(d)
		White	Wx		•	0.26	0.310	0.36	-	-
	Color	vvince	Wy			0.27	0.320	0.37	-	-
	Chromaticity	Ded	Rx			0.565	0.615	0.665	-	-
5	(Center point of	Red	Ry	$\theta = 0^{\circ}, \phi = 0^{\circ}$		0.301	0.351	0.401	-	-
	LCM) (CIE1931)		Gx	Ta=25°C	Ta=25°C		0.364	0.414	-	-
	Green		Gy				0.604	0.654	-	-
		Plue	Bx			0.1	0.150	0.2	-	-
		Blue	Ву			0.021	0.071	0.121	-	-
6	NTSC			59.4%				·	·	

Remarks:

- 1) EOC data above is measured using DMS-501 display measurement system.
- 2) Brightness data is measured using photometer Topcon BM-7.

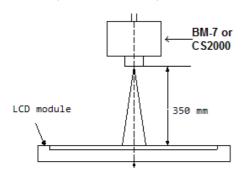




Note (c): Definition of Contrast Ratio

CR = Brightness at all pixels "White" / Brightness at all pixels "Black"

Note (d): backlight driving condition: If = 60mA Luminance measuring point: Center of the dot matrix under white pattern measuring setup as below figure:



9.0 BACKLIGHT SPECIFICATION

9.1 LED Backlight Electrical-Optical Characteristics

Item of Backlight Characteristics	Symbol	Min	Тур	Max	Unit	Condition		
Forward Voltage	Vf	-	3.2	-	V	1.lf=60mA, T=25°C 2.Aperture:1°,5 Points		
Uniformity	Δ	80	-	-	%	3.Average=min/max*100%		
Number of LED	-	3 Piece			-			
Connection Mode	S/P/M	3P -				-		
			1.Ta=25°C±5°C,					
			RH=60% ± 10%;					
	30000Hrs	(When the	lf=20mA/LED					
LED Lifetime	attenuatior	n ṫo 50% at	the beginn	2.No other Interference,				
	luminous intensity of time) such as Current, Voltag							
						suddenly rise,		
						Electrostatic shock, etc.		

Remarks: chromaticity and luminance data are measured using photometer Topcon BM-7.

10.0 RELIABILITY SPECIFICATION

10.1 Reliability Test Conditions

NI.								
No	Test Item	Test Conditions						
1	High Temperature Storage	+70°C, 240hrs						
2	High Temperature Operation	+60°C, 240hrs						
3	Low Temperature Storage	-30°C, 240hrs						
4	Low Temperature Operation	-20°C, 240hrs						
5	High Temperature Humidity Operation	+40°C, 90%RH, 240hrs						
6	Temperature Shock Storage	$-30^{\circ}C\pm 2^{\circ}C(30min) \sim 25^{\circ}C(5min) \sim 70^{\circ}C\pm 2^{\circ}C(30min), 10$ cycles.						
7	Vibration Test (Packaging)	Frequency:10-55Hz , Amplitude:0.75mm, x,y,z every direction for 0.5 hour						
8	Drop Test (Packaging)	Drop to the ground from 80cm height, 6 side of carton, each once						

Remarks:

1) For operation test, above specification is applicable when test pattern is changing during entire operation test.

2) Inspections after reliability tests are performed when the display temperature resumes back to room temperature.

3) It is a normal characteristic that some display abnormality can be seen during reliability test. If the display abnormality can recover as normal condition within 24 hours at room temperature, there is no permanent destruction over the display. The display still possesses its functionality and considered as acceptable after reliability tests.

10.2 Failure Judgment Criteria

After the reliability tests above, test sample shall be let return to room temperature and humidity for at least 4 hours before final tests are carried out.

Item	Acceptance Criteria
Electrical Characteristic	No electrical short and open.
	Increase in current consumption is less than 2 times of initial value.
Mechanical Characteristic	Within mechanical and drawing specification
Optical Characteristic	Within appearance standard as specified in this specification. Contrast ratio change & ON-transmission value shall not less than 50% of initial value.

11.0 QUALITY SPECIFICATION

11.1 Acceptable Quality Level (AQL)

Each lot should satisfy the quality level defined as follows:

- a) Inspection method: MIL-STD-105E Level II normal one time sampling
- b) AQL level

Category	AQL	Definition
Major	0.25%	Functional defective as product
Minor	0.25%	Satisfy all functions as product but not satisfy cosmetic standard

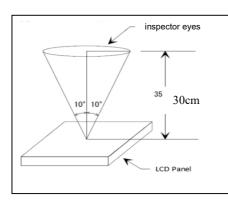
11.2 Conditions of Inspection

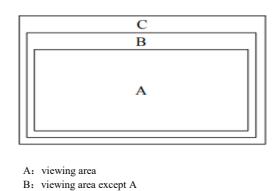
- a) Inspection illumination: Function illumination<150Lux; Appearance illumination is 2500±500Lux.
- b) Inspection distance: About 30cm between the observer's eyes and the LCD.
- c) Inspection angle: Normal inspection angle is +/-10 $^{\circ}$ form LCD.

(Ghost shadow inspection angle is $\pm/-45^{\circ}$; Light leakage inspection angle is $\pm/-30^{\circ}$)

d) Inspection environment: normal temperature (18~27°C) and normal humidity (50~85%RH)

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Note: As a general rule, visual defects in C is permissible, when it is no trouble for quality and assembly of customer's product.

11.3 Acceptance Criteria (DISPLAY Elektronik GmbH internal standard: IS-QC- 089(E)TFT-1)

C: Outside viewing area

a) Function Inspection

Item	Acceptance/Rejection Criteria					Classificatio n	Method	Method
Functional	 No-display /abnormal display/line defect etc.are not acceptable. Obvious color deviation in dark/red/green/blue screen is not acceptable. (refer limit sample if application) Obvious color deviation in the same screen is not acceptable. (spot, mura which cannot be seen by ND6 % is acceptable; Judgement Methods: The distance from the panel to ND filter paper: 350-400 - mm , put the ND filter paper in 1-2 cm distance away from the eye position, using monocular observation) The standard of eye Sight for Spot, Mura bad: put the filter paper in the positon in accordance with 3.0, move the eye sight away from the filter paper and turn the sight back to the filter paper. The standard of inspection time for spot, Mura:5 seconds. Current consumption (Idd MAX) shall not exceed the limit specified on the Test Instruction. Display character/ pattern shall be referred to the Test Instruction. 				Major	Visual	А	
Spot Foreign Particle, Dirt under POL or TP	6.0bvious light leakage	Width	Zone Size(mm) D≤0.15 0.15 <d≤0.2 D>0.2</d≤0.2 	Acc Unlin 3 0	nited	Major	Visual (Scale magnifying glass)	A、B、 C
		Defect Foreign body, Pit	Size(mm) W≤0.02 0.02 < W≤0.05 and L≤4.0 W≥0.05	Acc A, B Unlimited 2 (distance ≥ 5mm) Define as s	C	-		
Line defect: foreign or Scratch		Polarizer fibrous foreign body BL fibrous foreign body	W≤0.02 0.02 < W≤0.05 and L≤4.0 W≥0.05	Unlimited 2 (distance ≥ 5mm) Define as s	Unlimited pot defect	Minor	Visual (Scale magnifying glass)	A, B, C
			$W \le 0.02$ 0.02 < W ≤ 0.05 and L ≤ 4.0 W ≥ 0.05	Unlimited 2 (distance ≥ 5mm) Define as s	Unlimited pot defect			
Polarizer Air or TP film bubble	N/A	Δ	w≥0.03 Size(mm) D≤0.15 0.15 <d≤0.2< td=""> 0.2<d≤0.25< td=""></d≤0.25<></d≤0.2<>	A B Unlimited 3 1		Minor	Visual (Scale magnifying glass)	A、B、 C

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Production Specification

Item	Acceptance/Rejection Criteria				Classificatio n	Method	Method	
			D>0.25	0				
Light dot Dark dot Definition	 Pixel definition: Pixel is made of three sub-pixels (Red + Green +Blue) Dot definition: Dot is a sub-pixel (Red or Green or Blue) J. Light / Dark dot definition: A sub-pixel is on or off when the function testing. Light dot appears in dark picture usually. Dark dot appears in R/GB color picture or the white picture usually. Adjacent dot definition: Adjacent dot is made of two or three sub-pixels(R+G or G+B or B+R or R+G+B); 					Minor	Visual (Scale magnifying glass)	А
	1. If the	Defect	Acc No.	Rem	ark		Visual	
	bright/dark dot size is less than	light dot	3	0			(Scale magnifying	
	1/2 size of sub- pixel, ignore the dot.	light dot two- connection	1	vertical and diago not all	nal connetion are		(Scale magnifying glass) See the judgement method as below	
	2. If the	dark dot	3	1			method as below 双眼	
	bright/dark dot size is equal or more than 1/2	dark dot two- connection	1	vertical and diago not all				
	size of sub-pixel, follow the acceptable	dark dot three- connection	3	1			NDitter	
Bright dot/dark dot	number of dot Bright defect specified	er of dot specified table on ht. nt dot can seen by 6 shall the tiny dot Total tion	≤3	a two-connection dot count as 2 dots.	Minor	1.0 ND filter paper judgement method for bright dot and tiny bright dot: Distance from the ND filter paper to panel: 1-2 cm position, binocular observation	Α	
dot by Acc	4.Bright dot/dark dot can be seen by ND5% press Acc Qty standard judgement.			2.0The standard of eye-sight inspection for Bright dot and tiny Bright dot : put the filter paper in the				
	5.Tiny Bright dot def	inition, The bright dot ca	nnot be seen by NI	D 6%.			position in accordance with	
Tiny Bright dot	Tiny bright dot judgement, If the bright dot cannot be seen with ND6%, the acceptable Number is unlimited. If the bright dot can be seen with ND6%, the acceptable Number shall \leq 10. Bright						1.0, move the eye- sight away from the filter paper and then turn the sight back to the filter paper. The standard of inspection time for Light spot, Light spot 5 seconds.	
Distance Defect number	* 1 Distance between two detects must be more than 5 mm. *2.Total number of defects ≤3.					Minor	Visual (Scale magnifying glass)	А

b) Appearance Inspection

Item	Acceptance/Rejection Criteria				Classificat ion	Method	Method
	A.General chip-out	x (mm)	y (mm)	z (mm)	-		
		≪4.0	Outside 1/3 S	Ignore			
Chip-out					Minor	Visual (Scale magnifying glass)	Out of A
	S: Inr		Innerborder line of the seal				

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Production Specification

Item	Accepta	nnce/Rejection C	riteria		Classificat ion	Method	Method
	B. Chip-out on the back of terminal ledge	x (mm)	y (mm)	z (mm)			
		$\frac{\text{Ignore}}{\leqslant 4.0}$	≤0.3 ≤1/4L	$\frac{\leq 1/2t}{\leq t}$			
	C. Chip-out on the terminal ledge but not exactly on the ITO electrode.						
			y (mm) ≤0.3 ≤1/4L	z (mm) ≤1/2t ≤t			
	D. Chip-out on ITO electrode	x (mm)	y (mm)	z (mm)			
		Ignore ≤2. 0 ≤3. 0	≤0. 3 ≤0. 8 ≤0. 5	$ \begin{array}{c} \leqslant 1/2t \\ \leqslant 1/2t \\ \leqslant t \end{array} $			
	E. Chip-out at corner	x (mm)	y (mm)	z (mm)			
		≤3.0	≤3.0 or ≤1/4L (whichever is less)	≤T			
	F. Chip-out at corner	x (mm)	y (mm)	z (mm)		Visual	
		≤3.0 ≤3.0 ≤T Remark: L= contact pad length, T=Single thickness galss			Minor	(Scale magnifying glass)	Out of A
	G. Bur	x (mm)	y (mm)	z (mm)	-		
		unlimited	≪0.2	≤t			
	H. Crack line	Extended crack	t is not allowed		Majoy	Visual	Out of A
Foreign material		Zon	-	No.			
Black	Width	Size	A B Unlimited	С		Visual (Scale	
White dot、 Pit、Dent D=	Length D=(Length+Width)/2	0.15 <d≤0.2 D>0.2</d≤0.2 	3	Unlimit ed	Minor	magnifying glass)	A
Bubble etc. Foreign material Bubble etc.	W Defect Foreign body, Pit, Polarize r fibrous foreign			N	Minor	Visual (Scale magnifying glass)	
		Size (mm)	Acc A _N B	c No.			
		$\begin{array}{c} W \leq 0.02 \\ 0.02 < \\ W \leq 0.05 \text{ and} \\ L \leq 4.0 \end{array}$	Unlimited 2 (distance ≥ 5mm)	≥ Unlimit ed			А
	body	W≥0.05	Define as	spot defect			
Polarizer	N/A	Size(mn)	Acc	e No	Minor	Visual	A, B,

Item	Ассер	Classificat ion	Method	Method			
bubble or TP film			A, B	С		(Scale	С
bubble				magnifying glass)			
		0.15 < D≤0.2	3			glass	
		0.2 < D≤0.25	1	Unlimited			
		D > 0.25	0				
Distance	Distance between two detects must be more than 5 mm.				Minor	Visual (Scale magnifying glass)	А
LC bubble	Not acceptable.				Minor	Visual (Scale magnifying glass)	А
Polarizer	1.Polarizer dimension & position sh 2.Polarizer orientation shall meet th color shall be consistent with the sa	e requirement indicat		-	Minor	Visual (Scale magnifying glass)	Out of A
Protective film	 Protective film separating in Active Area is not acceptable. Fingerprint\ Massive dirt in the polarizer by protective film separating is not acceptable. Erasable smudginess must be cleaned, unerasable smudginess is allowed. 				Minor	Visual (Scale magnifying glass)	All
FPC	According to IPC-6013A.	ined, unerasable sind	iginess is anowed	••	_	Visual	_
cosmetic defect	- Visual						
	1.Coating location shall meet the m cover all terminal tracks.						
	2.RTV pin holes and bubble shall n						
RTV	3.RTV foreign material shall not ca						
(Tuffy)	4.Uncured coating is not acceptable				Majoy	Visual	Out of A
(5.RTV Coating cannot be damaged						
	6.RTV coating shall not exceed the over to the polarizer or the interface	hall not spread					
	7.Massive dirt on the coating is not						
	1. Backlight unit dimension and for	m shall meet the requ	irement on the dr	awing.	Majoy	caliper	Out of A
	2.Backlight not light up, or wrong l						
BLU	3. Acceptance criteria for dark spot defect and the line defect of the LC not acceptable. (Refer to the limit set						
	5.Light leak is not acceptable in ma applicable).	5.Light leak is not acceptable in main viewing direction. (Refer to the limit sample if applicable).					Out of A
	6. LCD shall not be lifted after asse		_				
	7.Backlight reflecting film can't sep						
Label	1.Label printing must clearly visible allowed.	in hole are not					
Printing	2.Date label on LCD cannot be mor assembly	Minor	Visual	Out of A			
The product	1.The outer dimension shall meet the	ne specification the dr	rawing.		Major	caliper	Out of A
shall be free of dirt.	2. The product shall be free of dirt.				Minor	Visual	Out of A

12.0 ENVIRONMENTAL SPECIFICATION

This product is designed, manufactured and compliant to below RoHS standard:

- 1. Cadmium and Cadmium Compounds
- 2. Hexavalent Chromium Compounds
- 3. Lead and Lead Compounds
- 4. Mercury and Mercury Compounds
- 5. Polybrominated Biphenyls (PBBs)
- 6. Polybrominated Diphenyl ethers (PBDEs)
- 7. Butyl benzyl phthalate (BBP)
- 8. Bis (2-ethylhexyl)phthalate (DEHP)
- 9. Dibutyl phthalate (DBP)
- 10. Diisobutyl phthalate(DIBP)

Less than 100ppm Less than 1000ppm Less than 1000ppm

13.0 GENERAL PRECAUTIONS FOR USING LCD MODULES

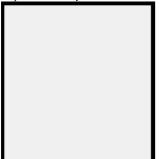
Handling Precaution	Operation Precautions
 No strong mechanical shock. LCD may be broken because it is made out of glass. Do not work on PCB. PCB may be cracked or damaged. Do not bend or process metal bezel positioning tab. LCD maybe shifted and LCD-PCB interconnection may be damaged, Do not scratch. Polarizer is soft material and can be easily scratched. Liquid crystal may leak when LCD/LCM is broken. Please wash your hands if you touch the liquid crystal. Wear gloves when handling LCD/LCM to avoid damage to LCD/LCM. Please do not touch electrodes with bare hands to avoid any contamination on connection. 	 Viewing angle can be adjusted by varying driving voltage, V₀ or Vop. Display performance may vary or show abnormal electro-optical performance when viewed at angle beyond the specified viewing angle range. Display color may change under extreme temperature. This is not destructive symptom and display color will resume back to normal when temperature goes back to normal temperature. Driving voltage shall be kept within the specified range as stated in this product specification. Overvoltage may shorten the LCD/LCM lifetime. No DC voltage to LCD/LCM. Electrical characteristics and reliability of LCD/LCM will deteriorate under DC. Please control the DC content in application driving circuit.
 Soldering Precaution on LCD/LCM Use soldering iron with proper grounding and no AC leakage. Temperature at tip of soldering iron: 330±10°C Type of solder: lead-free solder with resin flux fill. Soldering time: < 3sec. Soldering on LCD/LCM I/O terminal only. Do not apply force on the LCD metal pin when soldering. Metal pin connection to LCD terminal will be damaged or loosen by this external force under soldering temperature. Do not solder and de-solder for more than 3 times because metal pin connection or soldering pads will be damaged. 	 Avoid using the same display pattern for long time (continuous ON segment). It is a normal phenomena observed for passive driven display where image retention is observed when LCD is displayed with same pattern over 1 hour under temperature > 55°C. Customer is advised to design application software where display pattern will be changed from time to time, or using the N-line inversion function comes with the display driver IC. If the LCM is using master-slave configuration, customer is strongly recommended to use external Vo. If the LCM comes with MTP/OTP function, customer is recommended to use this MTP/OTP function for the best optical performance.
 Static Electricity Avoid static electricity. Please have proper ESD control and ground the human body and any electrical tools when assembling the LCD/LCM. Static electricity will be generated when peeling the protective film. It is a normal behavior that LCD/LCM will response to the static charges generated and will resume back to normal condition slowly. Peeling off the protective film in a correct way is very important to reduce the static electricity and its influence on LCD/LCM. It's recommended that the static electricity is controlled less than 1KV 	 FPC cleanness If ACF bonding is applied at customer side between FPC and PCB, cleaning on FPC and PCB bonding area (just before bonding) is a must to reduce risk of bonding reliability (eg bonding delamination/spring back phenomenon, low pull strength etc) Long-term Storage Conditions Store LCD/LCM in dark area and keep LCD/LCM away from direct sunlight and fluorescent light. Store LCD/LCM under temperature range of 0~35°C and room humidity of 50~60%RH.
by using ion fan and peeling off protective film slowly and in 45° angle, etc. Speed: Slowly peeling off the protective film to make sure static electricity less than 1KV. Angle: direction of removing protective film is 45+/-15°	 Possible Vop adjustment might be needed at customer side after prolong storage over 1 year from date of manufacturing.

14.0 APPENDIX

14.1 Functional testing pattern

Below test patterns will be used at all LCM functional tests at mass production stage. Acceptance of a product during inspection will be judged based on these test patterns only. Customer should notify DISPLAY Elektronik GmbH if different test patterns being used at customer side to ensure same testing platform between Customer and DISPLAY Elektronik GmbH, especially on those defects (flickering, image sticking, cross-talk, black/white line) which are pattern-dependent. These test patterns are by default agreed by both Customer and DISPLAY Elektronik GmbH, unless notified by Customer to revise such test patterns. If the defect listed in above description is seen in below pattern, LCD module should be judged as NG and vice versa.

1) White pattern



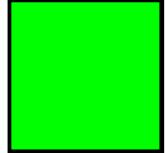
3) Grey pattern:



5) Gray Scale pattern:



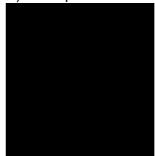
7) Green pattern:



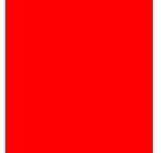
2) colour bar pattern:



4) Black pattern:



6) Red pattern:



8) Blue pattern:

